Abstracts

Flip-chip mounted, Ku band power amplifier compliant with space applications

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Following the trends of today's increased power density into power components arena, latest developments on advanced thermal management at component level are presented. Power flip chip technology was applied to commercial HB20P heterostructure bipolar transistor technology from UMS. Results of flip-chip mounted high power amplifier on Aluminum Nitride, packaged in a space compatible micro-package are discussed.

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